

L Number	Hits	Search Text	DB	Time stamp
1	60	((composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) near10 (polymer\$2 organic insulat\$3 dielectric) same (chip\$1 die\$1 dice\$1 circuit\$1 ic\$2)) same eutectic adj solder	USPAT	2004/08/19 10:48
2	60	((composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) near10 (polymer\$2 organic insulat\$3 dielectric) same (chip\$1 die\$1 dice\$1 circuit\$1 ic\$2)) same eutectic adj solder) and eutectic adj solder	USPAT	2004/08/19 10:48
-	31848	(composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) near10 (polymer\$2 organic insulat\$3 dielectric) same (chip\$1 die\$1 dice\$1 circuit\$1 ic\$2)	USPAT	2004/08/17 18:20
-	1524	((composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) near10 (polymer\$2 organic insulat\$3 dielectric) same (chip\$1 die\$1 dice\$1 circuit\$1 ic\$2)) and (composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) same (eutectic adj solder Pb\$1Sn lead near2 tin)	USPAT	2004/08/17 18:23
-	286	((composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) near10 (polymer\$2 organic insulat\$3 dielectric) same (chip\$1 die\$1 dice\$1 circuit\$1 ic\$2)) and (composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) same eutectic adj solder	USPAT	2004/08/19 10:46
-	1431	((composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) near10 (polymer\$2 organic insulat\$3 dielectric) same (chip\$1 die\$1 dice\$1 circuit\$1 ic\$2)) and (composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) same (eutectic adj solder Pb\$1Sn lead near2 tin)) and (composition\$1 resin\$4 epox\$3 encapsula\$4 paste slurr\$3 adhe\$4 underfill\$3) same (particles ball\$1 solid\$1 solder\$1 spher\$2)	USPAT	2004/08/17 18:25